

Single N-Channel MOSFET

■ DESCRIPTION

SMC3322 is the N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced trench technology devices are well suited for high efficiency fast switching applications, low in-line power loss are needed in small outline surface mount package.

■ PART NUMBER INFORMATION

SMC 3322 SN - TR G

a	b	c	d	e
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a : Company name.

b : Product Serial number.

c : Package code SN: SOT-23

d : Handling code TR: Tape&Reel

e : Green produce code G: *RoHS Compliant*

■ FEATURES

$V_{DS} = 30V, I_D = 5.4A$

$R_{DS(ON)} = 23m\Omega(\text{Typ.}) @ V_{GS} = 10V$

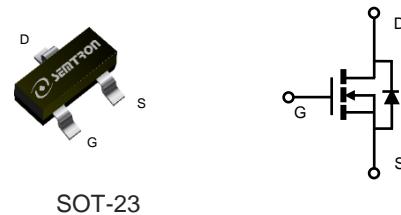
$R_{DS(ON)} = 25m\Omega(\text{Typ.}) @ V_{GS} = 4.5V$

$R_{DS(ON)} = 30m\Omega(\text{Typ.}) @ V_{GS} = 2.5V$

- ◆ Fast switch
- ◆ Improved dv/dt capability
- ◆ High power and current handling capability

■ APPLICATIONS

- ◆ Hand-Held Instruments
- ◆ Load Switch



SOT-23

■ ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-Source Voltage	30	V
V_{GSS}	Gate-Source Voltage	± 12	V
I_D	Continuous Drain Current $T_A=25^\circ C$	5.4	A
		$T_A=70^\circ C$	A
I_{DM}	Pulsed Drain Current ^A	21.6	A
P_D	Power Dissipation ^B $T_A=25^\circ C$	1.3	W
		$T_A=70^\circ C$	W
T_J	Operation Junction Temperature	-55/150	$^\circ C$
T_{STG}	Storage Temperature Range	-55/150	$^\circ C$

■ THERMAL RESISTANCE

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient ^C $t \leq 10s$		95	$^\circ C/W$
	Thermal Resistance Junction to Ambient ^C Steady-State		130	

ELECTRICAL CHARACTERISTICS($T_A = 25^\circ\text{C}$ Unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit	
Static Parameters							
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	30			V	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	0.4	0.7	1	V	
I_{GSS}	Gate Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 12\text{V}$			± 100	nA	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}$ $T_J = 25^\circ\text{C}$			1	μA	
		$V_{DS} = 24\text{V}, V_{GS} = 0\text{V}$ $T_J = 75^\circ\text{C}$			10		
$R_{DS(\text{ON})}$	Drain-source On-Resistance ^D	$V_{GS} = 10\text{V}, I_D = 5.4\text{A}$	23	27		$\text{m}\Omega$	
		$V_{GS} = 4.5\text{V}, I_D = 4.3\text{A}$	25	30			
		$V_{GS} = 2.5\text{V}, I_D = 3.2\text{A}$	30	38			
G_f	Forward Transconductance	$V_{DS} = 10\text{V}, I_D = 3\text{A}$		7		S	
Diode Characteristics							
V_{SD}	Diode Forward Voltage ^B	$I_S = 1\text{A}, V_{GS} = 0\text{V}$		0.7	1	V	
I_S	Continuous Source Current				1.8	A	
Dynamic and Switching Parameters							
$Q_g(10\text{V})$	Total Gate Charge	$V_{DS} = 15\text{V}, V_{GS} = 10\text{V}$ $I_D = 5\text{A}$		17	23	nC	
$Q_g(4.5\text{V})$	Total Gate Charge			8.7	11.7		
Q_{gs}	Gate-Source Charge			1.2	1.6		
Q_{gd}	Gate-Drain Charge			2	2.7		
C_{iss}	Input Capacitance	$V_{DS} = 15\text{V}, V_{GS} = 0\text{V}$ $f = 1\text{MHz}$		670	938	pF	
C_{oss}	Output Capacitance			54	76		
C_{rss}	Reverse Transfer Capacitance			45	63		
$t_{d(on)}$	Turn-On Time ^E	$V_{DD} = 15\text{V}, V_{GEN} = 10\text{V},$ $R_G = 3\Omega, I_D = 1\text{A}$		4.2		nS	
t_r				14			
$t_{d(off)}$	Turn-Off Time ^E			22			
t_f				6.5			

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

A. The value of $R_{\theta JA}$ is measured with the device in a still air environment with maximum junction temperature $T_J(\text{MAX}) = 150^\circ\text{C}$ (initial temperature $T_A = 25^\circ\text{C}$).

B. The $T_J(\text{MAX}) = 150^\circ\text{C}$, using junction-to-ambient thermal resistance.

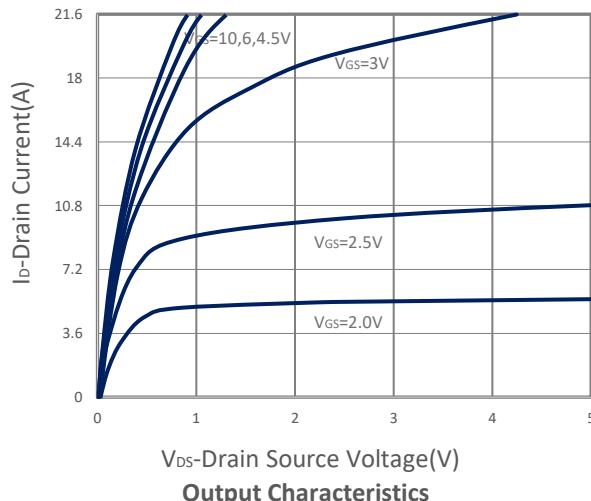
C. Surface-mounted on FR-4 board using 1 sq-in pad, 2 oz Cu, in a still air environment with $T_A = 25^\circ\text{C}$.

D. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$

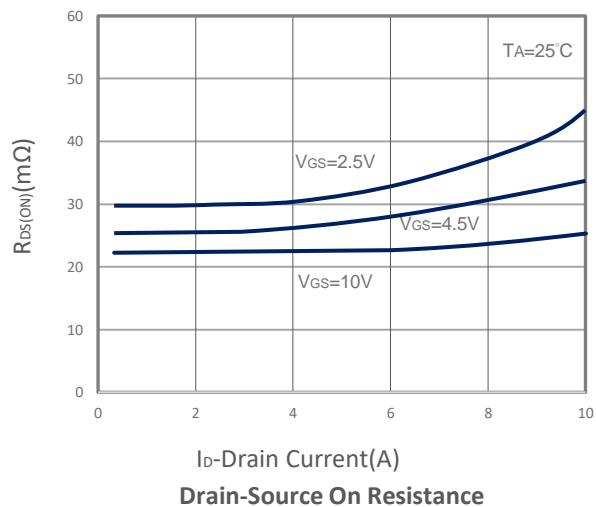
E. Pulsed width limited by maximum junction temperature.

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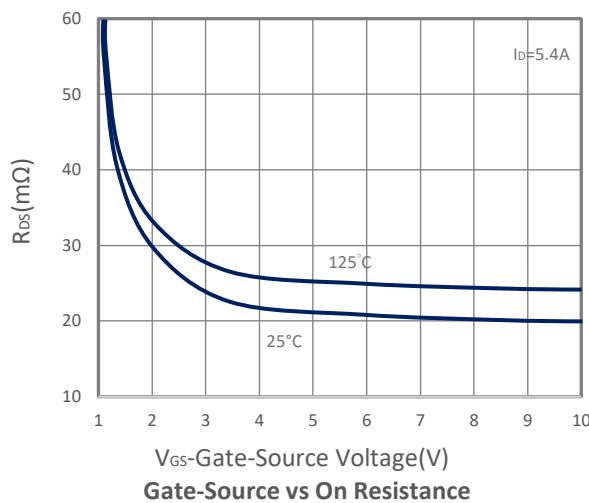
TYPICAL CHARACTERISTICS



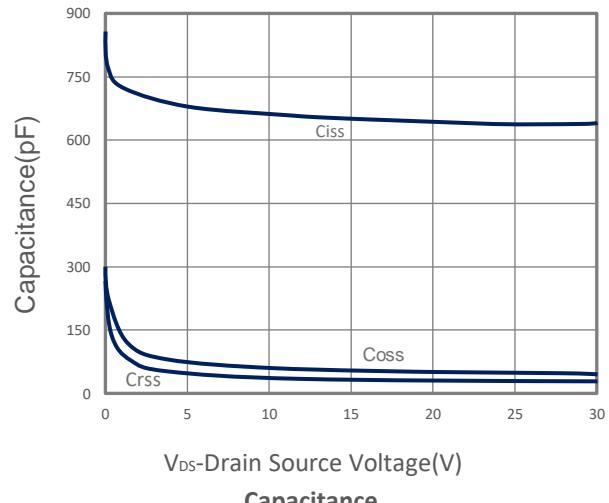
Output Characteristics



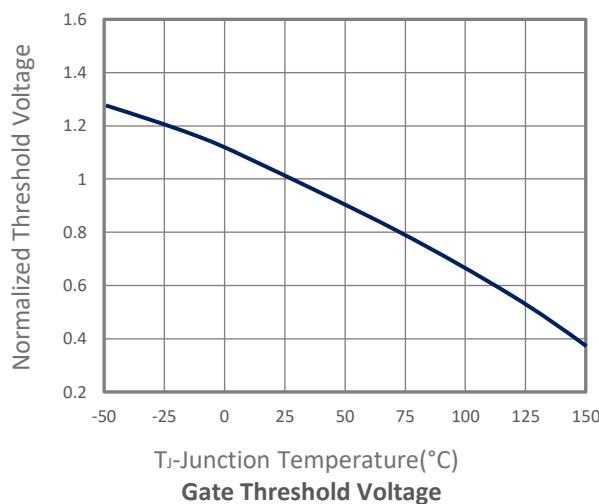
Drain-Source On Resistance



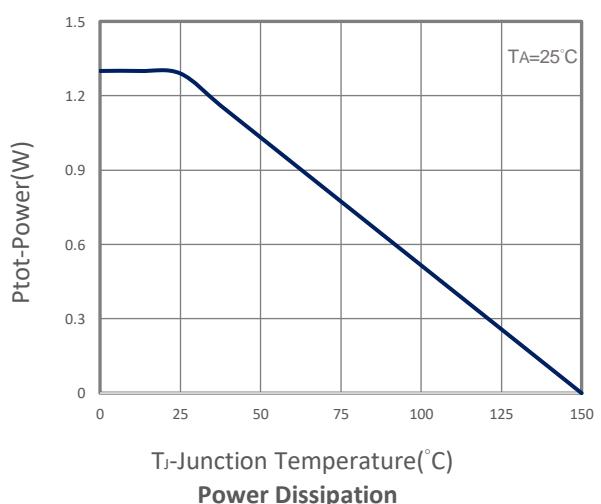
Gate-Source vs On Resistance



Capacitance

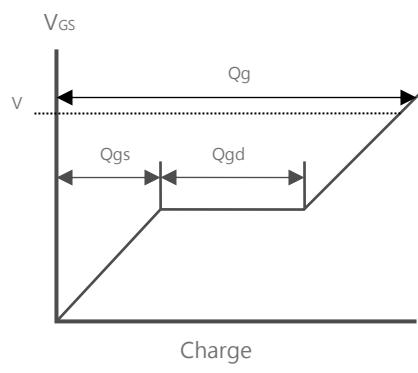
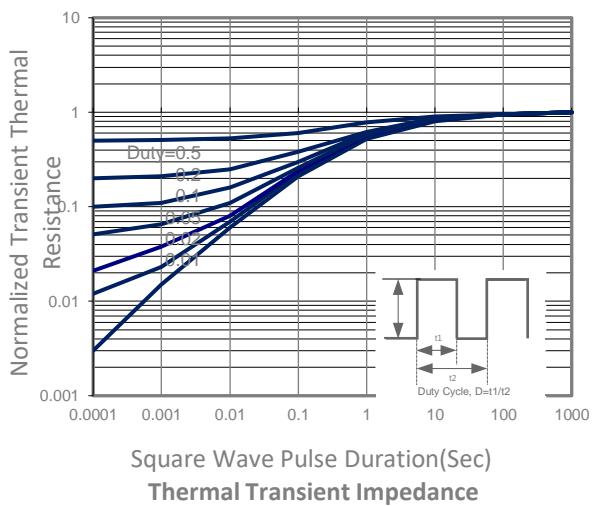
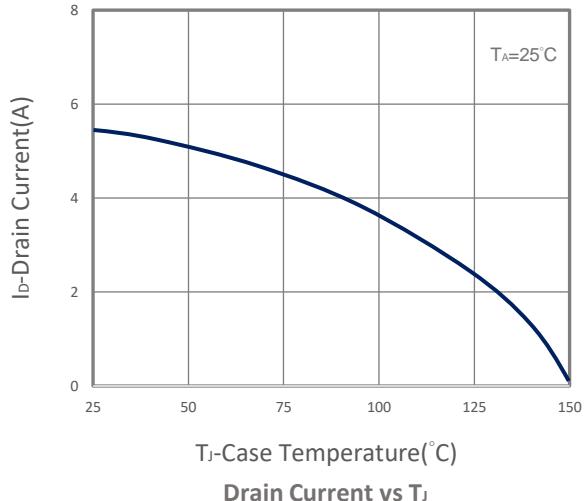
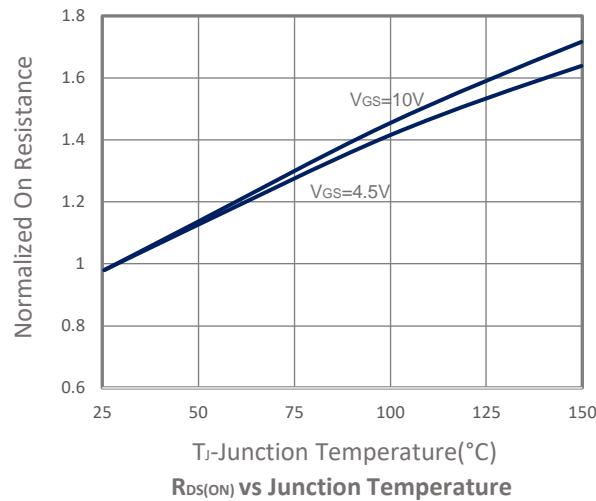


Gate Threshold Voltage

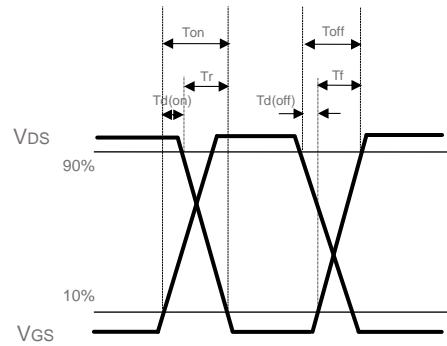


Power Dissipation

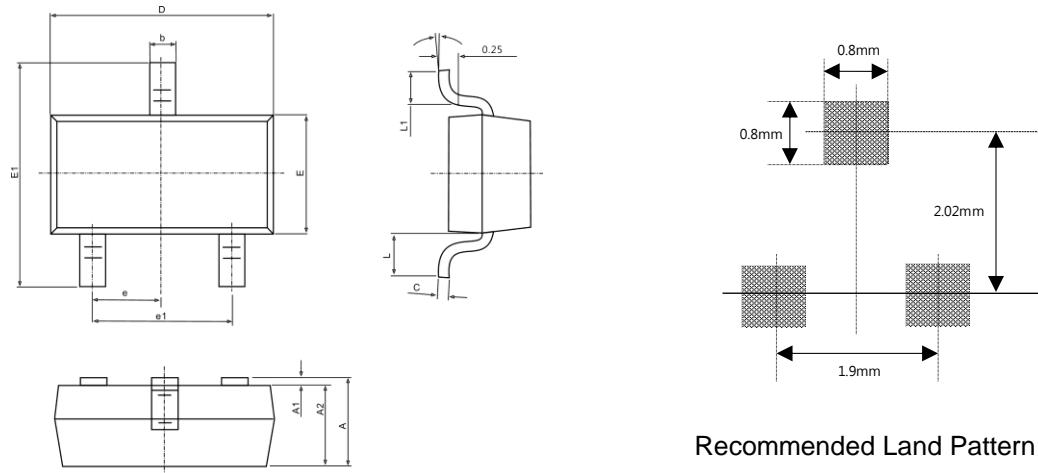
TYPICAL CHARACTERISTICS



Gate Charge Waveform



Switching Time Waveform

SOT-23 PACKAGE DIMENSIONS


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	-	1.050	-	0.041
A1	0.000	0.100	0.000	0.004
A2	0.900	1.100	0.035	0.043
b	0.390	0.450	0.015	0.018
c	0.050	0.150	0.002	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.300	2.500	0.091	0.098
e	0.950 TYP.		0.037 TYP.	
e1	1.900 REF.		0.075 REF.	
L	0.550 REF.		0.022 REF.	
L1	0.200	-	0.008	-
θ	0°	10°	0°	10°